Reportable Substances in Components

Package Type :	Component Weight :		0.1526 grams
SOIC(0.150")	Document No :	SOICN-16LD-PBY-RS-3	
Lead #: 16	Process Type :	Standard D/A & Lead Finish	

No	Material	Content in %	Content in gram	Substance Name	CAS No	Content in gram	% to Content	% to Unit	PPM
1	Molding Compound	57.14%	0.0872						
				Silica Fused	60676-86-0	0.07560	86.70%	49.54%	
				Epoxy Resin	Trade secret	0.00523	6.00%	3.43%	
				Epoxy, Cresol Novolac	29690-82-2	0.00174	2.00%	1.14%	
				Phenol Resin	Trade secret	0.00436	5.00%	2.86%	
				Carbon Black	1333-86-4	0.00026	0.30%	0.17%	
2	Copper Alloy Frame	37.29%	0.0569						
				Cu	7440-50-8	0.0555	97.54%	36.37%	
				Fe	7439-89-6	0.0013	2.28%	0.85%	
				P	7723-14-0	0.0000	0.02%	0.01%	59
				Zn	7440-66-6	0.0001	0.18%	0.07%	655
3	Spot Silver Plating	0.39%	0.0006						
				Ag	7440-22-4	0.00060	100.00%	0.39%	
4	Silver Die Attach Epoxy	0.79%	0.0012						
				Silver	7440-22-4	0.00090	75.00%	0.59%	
				Epoxy Resin	9003-36-5	0.00018	15.00%	0.12%	
				1,4-Bis (2,3-epoxypropoxy)butane	2425-79-8	0.00006	5.00%	0.04%	393
				Aromatic Amine	Trade secret	0.00006	5.00%	0.04%	393
5	Gold Wire	0.20%	0.0003						
				Au	7440-57-5	0.00030	100.00%	0.20%	
				Be	7440-41-7	0.00000	0.00%	0.00%	<1
6	External Lead Plating	2.56%	0.0039						
				Sn	7440-31-5	0.00390	100.00%	2.56%	
7	Silicon Die	1.64%	0.0025						
				Si	7440-21-3	0.00250	100.00%	1.64%	

Rev	ECN	Originator	Change	Reason
A	090804SB09	E. Yoon	New release.	New
B	112806HC28	E. dlSantos	Amend CAS no. of SiO2	Per Kamie S.
C	043010HC01	S. YEH	Update molding compound	Per Kamie S.